Low-Power High-Speed 90-nm CMOS Clock Drivers

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Register Array Modules



Power Dissipation and Signal Propagation Delay of a Single Logic Gate

Power due to dynamic current

 $p_{\rm D}(n) = (\mathbf{A}n + \mathbf{B}) \cdot V_{\rm D}^2 \cdot f$

Power due to short-circuit current

$$p_{\rm S}(m,n) = \frac{\mathrm{E}(m+\mathrm{F})^{\mathrm{G}} \cdot (V_{\mathrm{D}} - 2V_{\mathrm{T}})^3 \cdot f}{(1+\mathrm{H}n)^{\mathrm{J}}}$$

Signal Propagation Delay

$$t_{d} \approx \frac{(C_{m} + C_{n})V_{D}^{2}}{\frac{\beta}{2}(V_{D} - V_{th})^{2}} \approx \frac{2(C_{m} + C_{n})}{\beta(V_{D} - V_{th})}$$
$$\propto (Am + B) + (An + B) = A(m + n) + 2B$$
$$= A(m + \frac{M}{m}) + 2B$$



at m = 1 & m = M $t_d \propto A(M+1)+2B$

at m = n $t_{\rm d} \propto 2AM^{0.5} + 2B$

Signal Propagation Delay of 90-nm Register Array Modules (SPICE Simulation)



Signal Propagation Delay of 90-nm Register Array Modules (SPICE Simulation)



Signal Propagation Delay (t_T) & Optimized *m* for Minimum t_T of 90-nm Register Array Modules (SPICE Simulation)



Power Dissipation of 90-nm Register Array Modules (SPICE Simulation)



Power Dissipation (P_T) & Optimized *m* for Minimum P_T of 90-nm Register Array Modules (SPICE Simulation)



90-nm CMOS LSI Chip with 6 Register Array Modules

	Technology: 90-nm,Triple-Well, 6-Layer, Cu, CMOS Chip Size: 2.5 mm × 2.5 mm
Register Array Modules	No. of D-FF $(M = m \times n) = 40$ m n = M/m 1 40 5 8 8 5 10 4 20 2 40 1

Power Dissipation of 90-nm Register Array Modules (Experimental Results)

